



Material Content Data Sheet



Sales Product Name				IPZ40N04S5-5R4		Issued		9. June 2015	
MA#				MA001171642					
Package				PG-TSDSON-8-32		Weight*		35.31 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	0.262	0.74	0.74	7424	7424	
leadframe	inorganic material	phosphorus	7723-14-0	0.003	0.01		88		
	non noble metal	zinc	7440-66-6	0.012	0.04		352		
	non noble metal	iron	7439-89-6	0.249	0.70		7047		
wire	non noble metal	copper	7440-50-8	10.102	28.61	29.36	286123	293610	
	noble metal	gold	7440-57-5	0.030	0.09	0.09	862	862	
	encapsulation	organic material	carbon black	1333-86-4	0.037	0.11		1059	
encapsulation	plastics	epoxy resin	-	1.925	5.45		54533		
	inorganic material	silicondioxide	60676-86-0	16.730	47.39	52.95	473855	529447	
leadfinish	non noble metal	tin	7440-31-5	0.400	1.13	1.13	11337	11337	
plating	noble metal	silver	7440-22-4	0.086	0.24	0.24	2425	2425	
solder	noble metal	silver	7440-22-4	0.012	0.03		337		
	non noble metal	tin	7440-31-5	0.010	0.03		270		
	non noble metal	lead	7439-92-1	0.455	1.29	1.35	12886	13493	
heatspreader	inorganic material	phosphorus	7723-14-0	0.001	0.00		17		
	non noble metal	zinc	7440-66-6	0.002	0.01		67		
	non noble metal	iron	7439-89-6	0.047	0.13		1331		
heat sink CLIP	non noble metal	copper	7440-50-8	1.908	5.40	5.54	54029	55444	
	inorganic material	phosphorus	7723-14-0	0.001	0.00		26		
	non noble metal	zinc	7440-66-6	0.004	0.01		103		
	non noble metal	iron	7439-89-6	0.073	0.21		2063		
*deviation	non noble metal	copper	7440-50-8	2.958	8.38	8.60	83766	85958	
						Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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